ARK Menu >







Performance

Processor Base Frequency

PCI Express Revision

Low Halogen Options Available

Intel® AES New Instructions

Secure Key

# of Cores

# of Threads

Specifications Essentials Performance Memory Specifications **Graphics Specifications Expansion Options Package Specifications** Advanced Technologies Intel® Data Protection Technology Intel® Platform Protection Technology Compatible Products Ordering / sSpecs / Steppings

Download Drivers

Specifications	
- Essentials	
Status	End of Life
Launch Date	Q1'13
Processor Number	i3-3210
Cache	3 MB SmartCache
Bus Speed	5 GT/s DMI
Instruction Set	64-bit
Instruction Set Extensions	SSE4.1/4.2, AVX
Embedded Options Available	No
Lithography	22 nm
Thermal Solution Specification	20110
Recommended Customer Price	\$117.00
Conflict Free	Yes
Datasheet	Link

Related Products 3rd Generation Intel® Core\* i3 Processors Intel® Core® i3-3200 Desktop Processor Series Products formerly Ivy Bridge

Compare



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## Quick Links

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## PCN/MDDS Information SROYY 923855: PCN | MDDS 926157: PCN 926166: PCN | MDDS

IDP	55 W
Memory Specifications	
Max Memory Size (dependent on memory type)	32 GB
Memory Types	DDR3 1333/1600
Max # of Memory Channels	2
Max Memory Bandwidth	25.6 GB/s
ECC Memory Supported ‡	No

2

4

3.2 GHz

Processor Graphics ‡		Intel® HD Graphics 2500
Graphics Base Frequency		650 MHz
Graphics Max Dynamic Frequency		1.05 GHz
Intel® Quick Sync Video	Q	Yes
Intel® InTru™ 3D Technology		Yes
Intel® Insider™		Yes
Intel® Wireless Display	Q	Yes
Intel® Flexible Display Interface (Intel® FDI)		Yes
Intel® Clear Video HD Technology		Yes
# of Displays Supported #		3
Device ID		0x152

PCI Express Configurations ‡	up to 1x16, 2x8, 1x8 & 2x4
Package Specifications	
Max CPU Configuration	1
TCASE	65.3°C
Package Size	37.5mm x 37.5mm
Sockets Supported	FCLGA1155

2.0

See MDDS

Advanced Technologies		
Intel® Turbo Boost Technology ‡		No
Intel® vPro Technology ‡	Q	No
Intel® Hyper-Threading Technology ‡	Q	Yes
Intel® Virtualization Technology (VT-x) #		Yes
Intel® Virtualization Technology for Directed I/C (VT-d) ‡	<b>Q</b>	No
Intel® VT-x with Extended Page Tables (EPT) #	Q	Yes
Intel® 64 ‡	Q	Yes
Intel® My WiFi Technology		Yes
Idle States		Yes
Enhanced Intel SpeedStep® Technology	Q	Yes
Thermal Monitoring Technologies		Yes
Intel® Identity Protection Technology ‡		Yes
O leading Date Date at Table 1		
Intel® Data Protection Technology		

rusted Execution Technology ‡	Q	lo
Execute Disable Bit ‡	,	es es
Anti-Theft Technology	,	es es

Q No

No

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"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2675QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact OEM for the BIOS that includes the latest Processor configuration update.

‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications [motherboard, ] processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and for operating system) for feature compatibility. Functionality,

performance, and other benefits of this feature may vary depending on system configuration. \*Conflict free" and \*conflict-free" means \*DRC conflict free", which is defined by the U.S. Securities and Exchange Commission rules to mean products that do not contain conflict minerals [tin, tantalum, tungsten]

and/or gold) that directly or indirectly finance or benefit armed groups in the Democratic Republic of the Congo [DRC] or adjoining countries. Intel also uses the term "conflict-free" in a broader sense to refer to suppliers, supply chains, smelters and refiners whose sources of conflict minerals do not finance conflict in the DRC or adjoining countries. Intel processors manufactured before January 1, 2013 are not confirmed conflict free. The conflict free designation refers only to product manufactured after that date. For Intel Boxed Processors, the conflict free designation refers to the processor only, not to any additional included accessories, such as heatsinks/coolers. See http://www.intel.com/content/www/us/en/architecture-and-technology/hyper-threading-technology.html?wapkw=hyper+threading for more information including details on which

processors support Intel® HT Technology. Max Turbo Frequency refers to the maximum single-core processor frequency that can be achieved with Intel® Turbo Boost Technology. See www.intel.com/technology/turboboost/ for more information.

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Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet US-709. requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

For benchmarking data see http://www.intel.com/performance. Intel processor numbers are not a measure of performance. Processor numbers differentiate features within each processor family, not across different processor families. See http://www.intel.com/content /www/us/en/processors/processor-numbers.html for details.

Processors that support 64-bit computing on Intel® architecture require an Intel 64 architecture-enabled BIO5.

⊕ USA (English)

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